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MOUNTING METHOD FOR SEMICONDUCTOR ELEMENTS

Inventor:	Yoshikazu Fujimori Seiko Epson K.K. 3-3-5 Daiwa, Suwa-shi, Nagano-ken
Applicant:	000002369 Seiko Epson K.K. 2-4-1 Nishi-shinjuku, Shinjuku-ku, Tokyo

Agent:

Yoshisaburo Suzuki,
patent attorney,
and 1 other

[There are no amendments to this patent.]

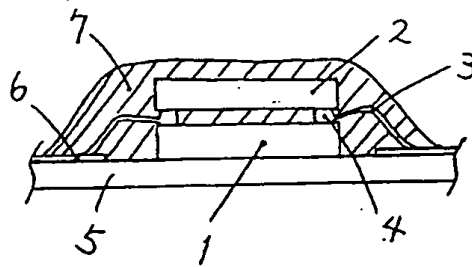
Abstract (There are amendments.)

Constitution

By utilizing the top of the circuit constitutional surface (hereafter referred to as the "active surface") of semiconductor elements (1) and (2), the active surfaces of two semiconductor elements are joined for the two to oppose utilizing wire bonding part (4) of one semiconductor element.

Effect

The semiconductor elements can be mounted at a higher density than the conventional mounting method, the number of wirings which connect the semiconductor elements and the external circuits can be reduced compared to the conventional technology, and the reliability is improved.



Claim

A mounting method for semiconductor elements characterized by the fact that in a mounting method for semiconductor elements, after executing electrical connection according to wire bonding, another semiconductor element is electrically connected to the same bonding wire in a state of the circuit constitutional surfaces of the semiconductor elements being opposed.

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